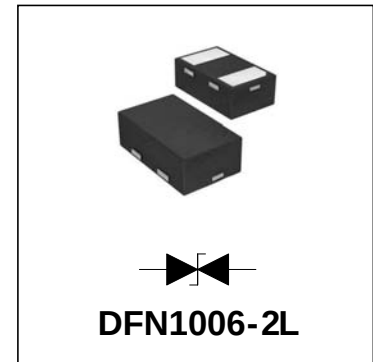


Features

- Protects one I/O or power line
- Ultra Low Capacitance: 0.35pF
- Working Voltage: 3.3 V
- Low Leakage Current



IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 20\text{kV}$ (air), $\pm 20\text{kV}$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 4.5A (8/20 μs)

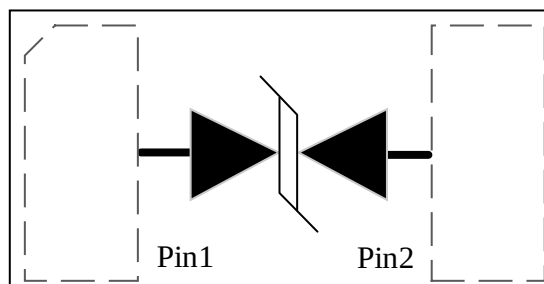
Mechanical Characteristics

- DFN-2L package
- Molding compound flammability rating: UL 94V-0
- Marking: Marking Code
- Packaging: Tape and Reel per EIA 481
- RoHS/WEEE Compliant

Applications

- Laptop Computers
- Cellular Phones
- Digital Cameras
- Personal Digital Assistants (PDAs)

Schematic & PIN Configuration

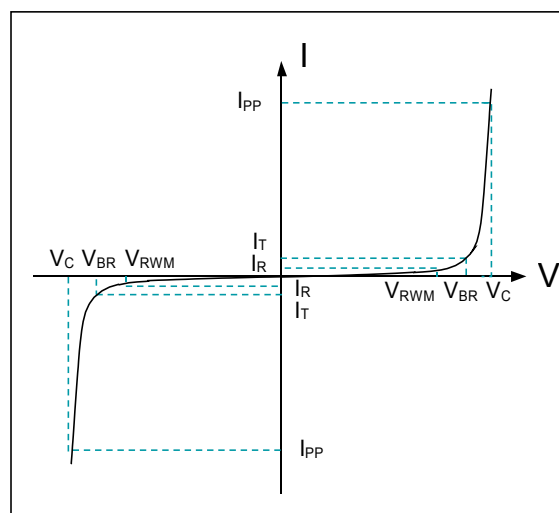


Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	110	Watts
Peak Pulse Current ($t_p = 8/20\mu s$) (note1)	I_{pp}	4.5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	20 20	kV
Lead Soldering Temperature	T_L	260(10seconds)	$^{\circ}C$
Junction Temperature	T_J	-55 to + 150	$^{\circ}C$
Storage Temperature	T_{stg}	-55 to + 150	$^{\circ}C$

Electrical Parameters (TA = 25°C unless otherwise noted)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current



Note: 8/20 μs pulse waveform.

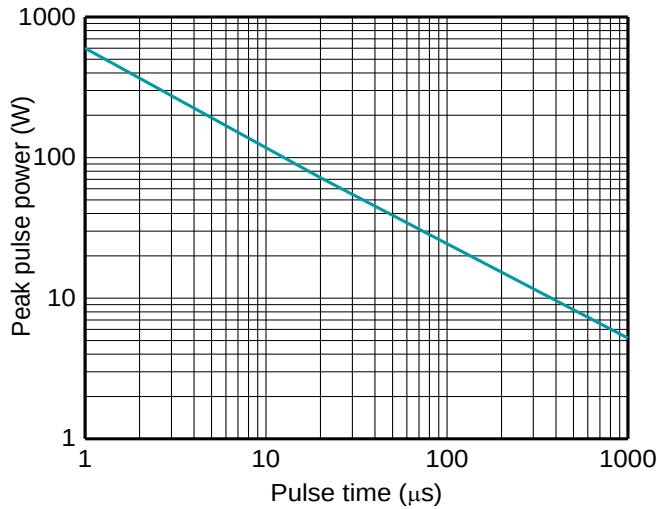
Electrical Characteristics

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				3.3	V
Reverse Breakdown Voltage	V_{BR}	$I_T = 1mA$	5.3		7.0	V
Reverse Leakage Current	I_R	$V_{RWM} = 3.3V$, $T = 25^{\circ}C$			0.1	μA
Clamping Voltage	V_C	$I_{PP} = 4.5A$, $t_p = 8/20\mu s$			22	V
Junction Capacitance	C_j	$V_R = 0V$, $f = 1MHz$		0.35	0.4	pF

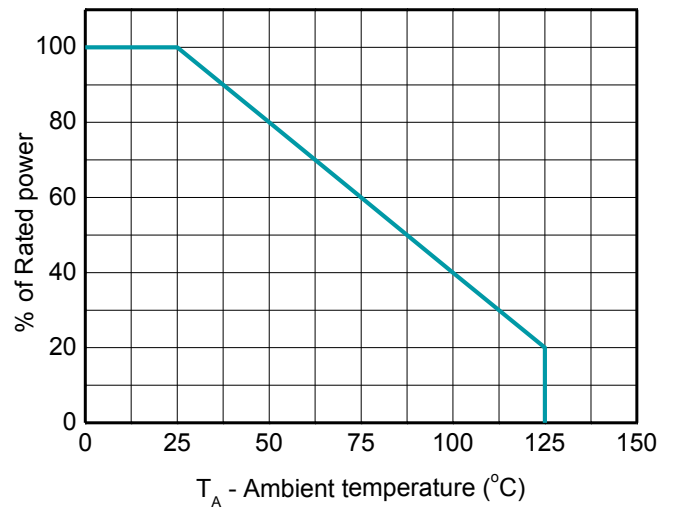
Note1: ESD Pulse Waveform according to IEC 61000-4-2. see Table1 and Figure4.

Note2: ESD tests Setup see Figure 5.

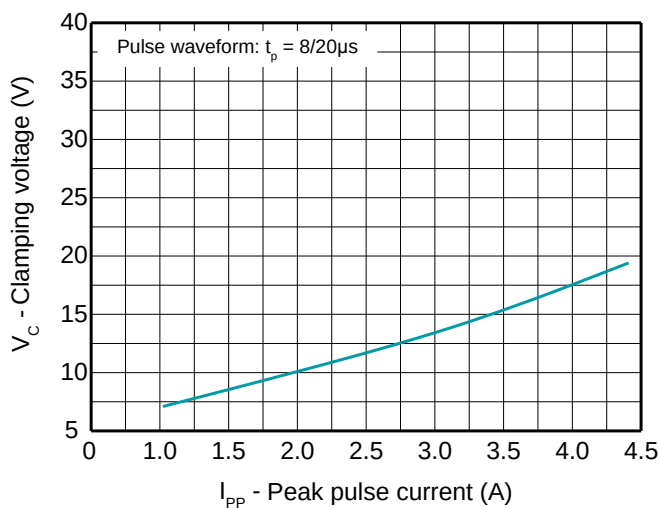
Typical Characteristics



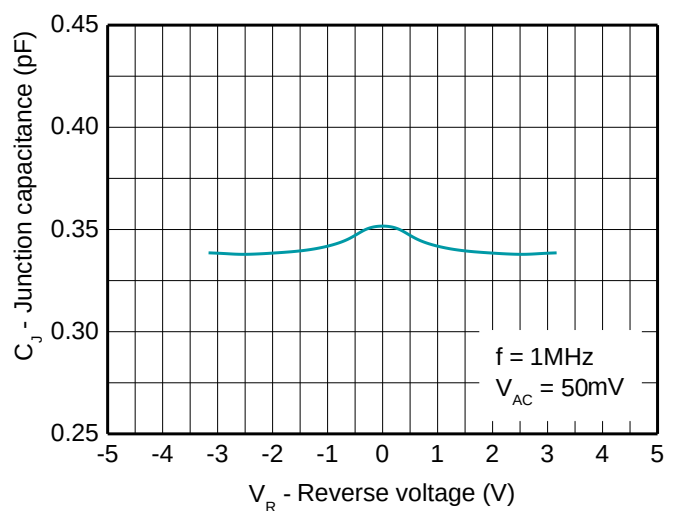
Non-repetitive peak pulse power vs. Pulse time



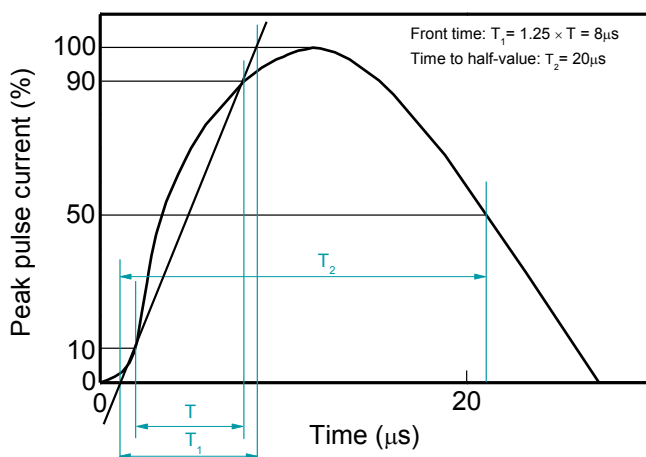
Power derating vs. Ambient temperature



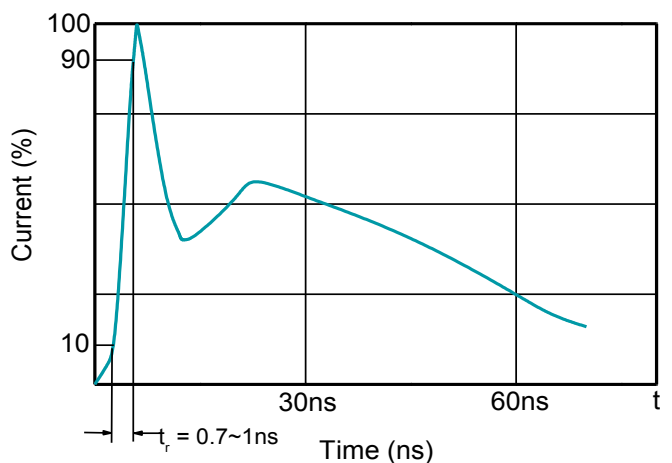
Clamping voltage vs. Peak pulse current



Capacitance vs. Reverse voltage

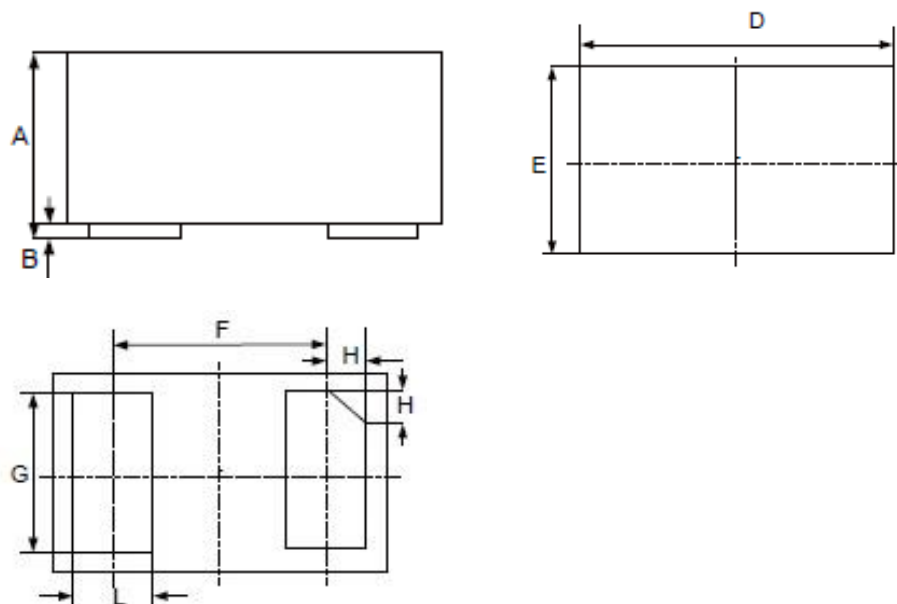


8/20 μs waveform per IEC61000-4-5



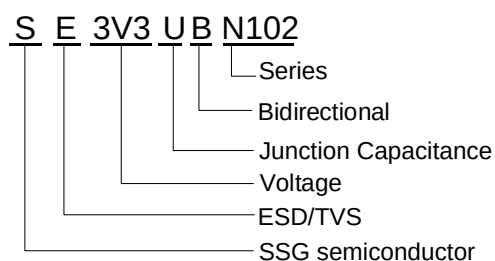
Contact discharge current waveform per IEC61000-4-2

Outline Drawing – DFN1006



DIM	MILIMETER	
	MIN (mm)	MAX (mm)
A	0.34	0.55
B	0	0.05
D	0.95	1.08
E	0.55	0.68
F	0.65(Typ)	
G	0.40	0.60
H	0.07	0.17
L	0.20	0.30

Part Numbering System



Device	Package	Shipping	Marking	Parameter
SE3V3UBN102	DFN1006-2L	10000/Tape&Reel	3 *	3 = Product Code T = Device Code